BS EN IEC 61189-2-808:2024

BSI Standards Publication

Test methods for electrical materials, printed board and other interconnection structures and assemblies

Part 2-808: Thermal resistance of an assembly by thermal transient method

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National foreword

This British Standard is the UK implementation of EN IEC 61189-2-808:2024. It is identical to IEC 61189-2-808:2024.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 61189-2-808

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English Version

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-808: Thermal resistance of an assembly by thermal transient method (IEC 61189-2-808:2024)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures et assemblages d'interconnexion - Partie 2-808 : Résistance thermique d'un assemblage par la méthode du transitoire thermique (IEC 61189-2-808:2024)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-808: Thermischer Widerstand der dielektrischen Schicht durch thermische transiente Methode (IEC 61189-2-808:2024)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

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European foreword

The text of document 91/1935/FDIS, future edition 1 of IEC 61189-2-808, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-808:2024.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2025-02-28
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2027-05-30

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-808: Thermal resistance of an assembly by thermal transient method

FOREWORD

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IEC 61189-2-808 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1935/FDIS	91/1955/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed board and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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